

FPC Materials / Bonding Sheet [TFA-880 series]

Line up to Meet Every Applications (Flex-Rigid, Multilayer, COF, Stiffener)

Features and Benefits

- Line-Up to Meet Every Needs (Short Tact Time High Reliability, Green Material etc.)
- Good Processability and Suitable every adhesive target (TFA-880CC)
- Suitable for Chemical Desmear process for FPC Multi-Layer Products. (TFA-880CE)
- Top Ranked Reliability among Halogen/Antimony Free Material (TFA-880CA)
- Excellent Drilling Process Ability and Chemical Resistance (TFA-880CE, 880CA)

Applications

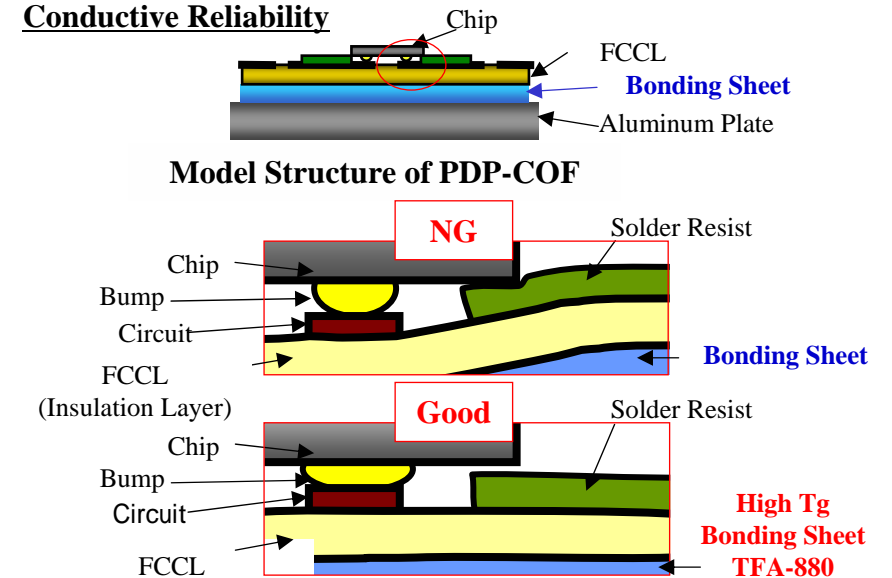
- Adhesion to Cable parts, Stiffener, Glass and PI-Film
- Multi-Layer FPC and Flex-Rigid for Cellular Phone and Digital Still Camera.
- Heat Resistance Type Bonding Sheet Using COF for Flat Panel Display.

Available Environmental Friendly Type (TFA-890)

General Property

Item	TFA-880CC 35	TFA-880CE 35	TFA-880CA 35
Resin flow	0.25mm	0.25mm	0.20mm
Heat Resistance	>260C 60sec.	>260C 60sec.	>260C 60sec.
Peel Strength (vs Cu)	-	1.25kN/m	1.37 kN/m
Peel Strength (vs. PI)	>3.00 kN/m	2.90 kN/m	2.53 kN/m
Tg	60C	80C	100C
Application	Stiffener Heat sink	Multilayer	Flex-Rigid COF

Conductive Reliability



There are cases that dent under the chip is occurred after mounting in case of low Tg of Bonding Sheet and it affects the Conductive reliability.

TFA-880CA : No.1 Result for PDP-COF in Japan

Item	TFA-880CA	Competitor
Tg	100C	40C
Dent (Bend on Chip Mounting)	Rare	Frequent
Reliability	Excellent	Poor